

主要材料/BOM 清单信息(Information of Material/BOM list):

材料			描述	供应商
1	基板	S53011BY2E	240X76. 3X0. 22	客供
2	晶圆	WSI530CD1E	1810*960 (μ m ²) *200um (U1)	客供
3	晶圆	WLN577GD1E	1192*1042 (μ m ²) *200um(U2)	客供
4	晶圆	WLN520GD2E	908*680 (μ m ²) *200um(U3)	客供
5	晶圆	WLN577GD1E	870*840 (μ m ²) *200um(U4)	客供
6	晶圆	WUM530SD2E	1347*1068 (μ m ²) *200um(U5)	客供
7	晶圆	WUM530SD2E	1464*960 (μ m ²) *200um (U6)	客供
8	晶圆	WUM530SD2E	1365*672 (μ m ²) *200um(U7)	客供
9	助焊剂	TACFlux026S	/	上海瑞纭电子科技有限公司
10	塑封料	EME-G311Q Type L ver.GR	/	东莞宽诚电子材料有限公司
11	Release Film (离型膜)	TB 50 μ m*142mm TOWA	/	东和半导体设备（上海）有限公司
12	焊膏	PasteF590 Sn99. 3Cu0. 7-89M4 (LH)	/	贺利氏招远(常熟)电子材料有限公司

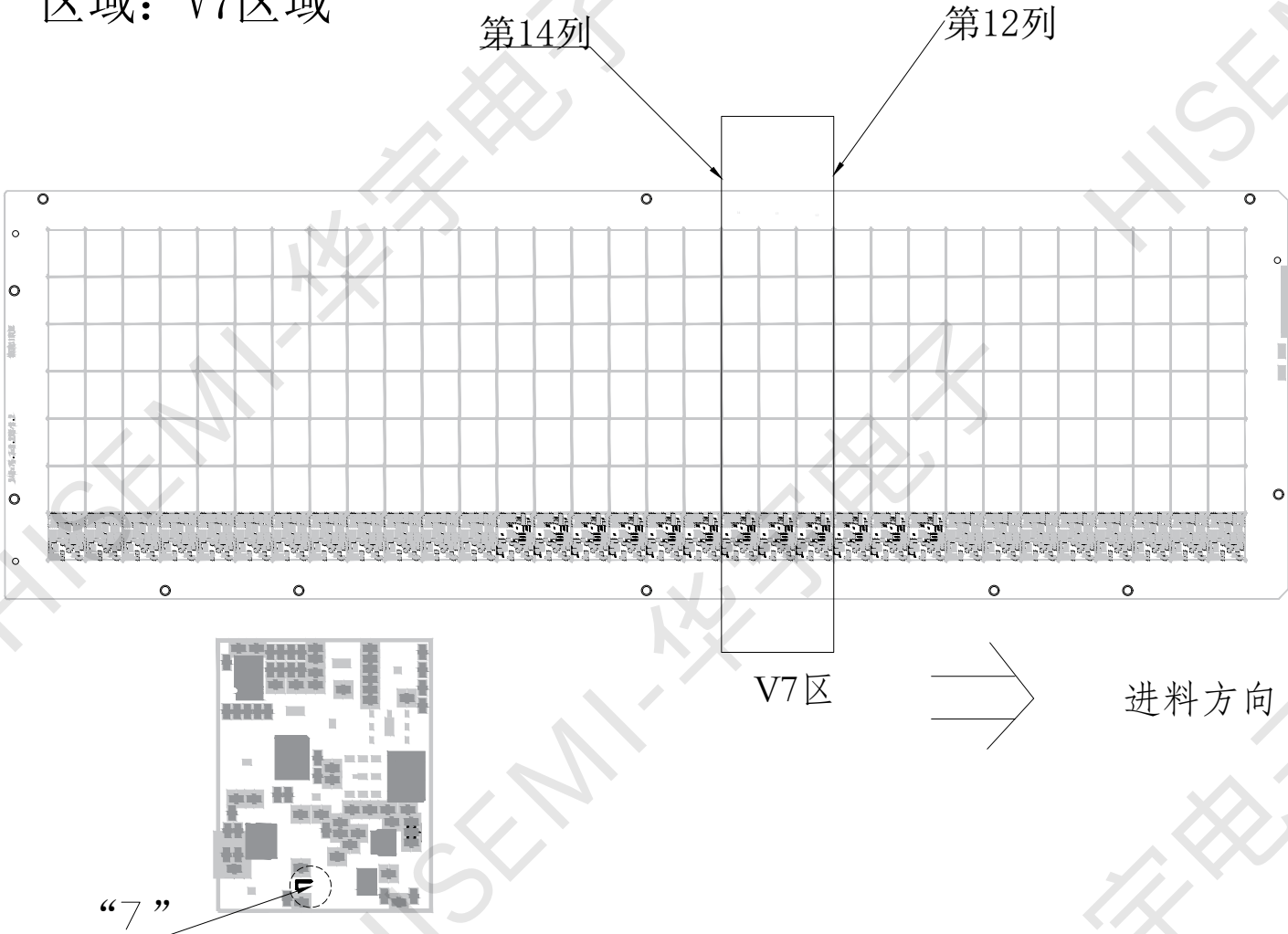
说明: HY-PX-1200-076 A 是HY-PX-1200-068 A 升级, 变更电感, 原图纸作废。

拟制 Prepared by		制图日期 Create Date	2025/12/9	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回答后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
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S53011BY2E贴装区域：MPW基板 贴装区域：V7区域

样品验证，禁止量产！



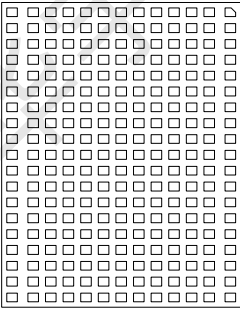
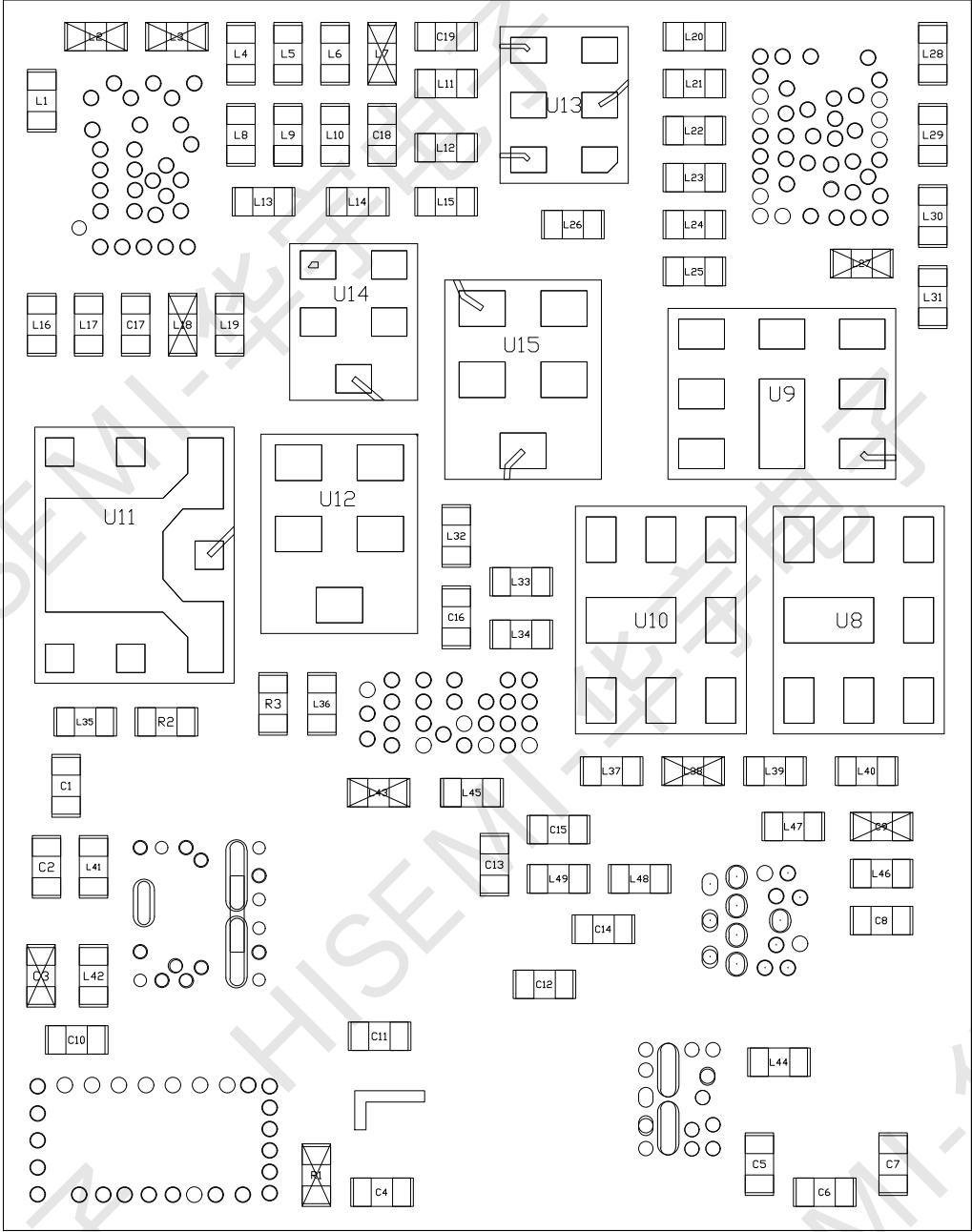
- 特殊说明：
- 1. 单颗unit有区域标识，生产请注意识别；
 - 2. U1/U2/U3/U4/U5/U6/U7芯片取片区域和对应TOPview见附页8-14；
 - 3. 注意U2对应信息如下：
 - ①U3注意指定wafer批次：24N1712, wsferID：Q5691018FE)
 - 4. 切割道宽度0.2mm。

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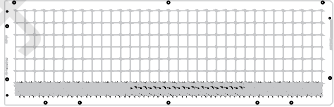
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样品验证，禁止量产！

PIN1



底部示意图

框架传送方向（装片）： L/F Direction (D/A)：三圆孔朝上	实物图： Chip photo:	特殊说明 Special Instructions：
		

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NO.	Item	Reference	value	package	KD P/N	Quantity
35	L22	LQP02TN10NH02D	10nH±3%	01005		1
36	L23	LQP02TN3N6B02D	3.6nH±0.1	01005		1
37	L24	LQP02TN3N7B02D	3.7nH±0.1	01005		1
38	L25	LQP02TN7N5H02D	7.5nH±3%	01005		1
39	L26	LQP02TN2N4B02D	2.4nH±0.1	01005		1
40	L28	LQP02TN22NH02D	22nH±3%	01005		1
41	L29	LQP02TN16NH02D	16nH±3%	01005		1
42	L30/L31	LQP02TN15NH02D	15nH±3%	01005		2
43	L32	LQP02HQ4N7H02E	4.7nH±3%	01005		1
44	L33/L47	LQP02HQ1N8B02E	1.8nH±0.1	01005		2
45	L34	LQP02HQ2N9B02E	2.9nH±0.1	01005		1
46	L35/L36	LQP02HQ4N0B02E	4.0nH±0.1	01005		2
47	L37/L39/L45	LQP02HQ13NH02E	13nH±3%	01005		3
48	L40	LQP02HQ6N2H02E	6.2nH±3%	01005		1
49	L41	LQP02HQ3N0B02E	3.0nH±0.1	01005		1
50	L42	LQP02HQ2N0B02E	2.0nH±0.1	01005		1
51	L44	LQP02HQ1N5B02E	1.5nH±0.1	01005		1
52	L46	LQP02HQ4N2B02E	4.2nH±0.1	01005		1
53	L48	LQP02HQ3N3B02E	3.3nH±0.1	01005		1
54	L49	LQP02HQ3N6B02E	3.6nH±0.1	01005		1
55	R2/R3	RTT0050000FH1	0Ω±1%	01005		2
56	R1	NA	NA	NA		0
57	C3	NA	NA	NA		0
58	C9	NA	NA	NA		0
59	L2	NA	NA	NA		0
60	L3	NA	NA	NA		0
61	L7	NA	NA	NA		0
62	L18	NA	NA	NA		0
63	L27	NA	NA	NA		0
64	L38	NA	NA	NA		0
65	L43	NA	NA	NA		0
66	基板	S53011BY2E	基板	/		1
67	锡膏	/	F590 SnCu0.7-89M4	/		/

NA表示不贴装元器件。

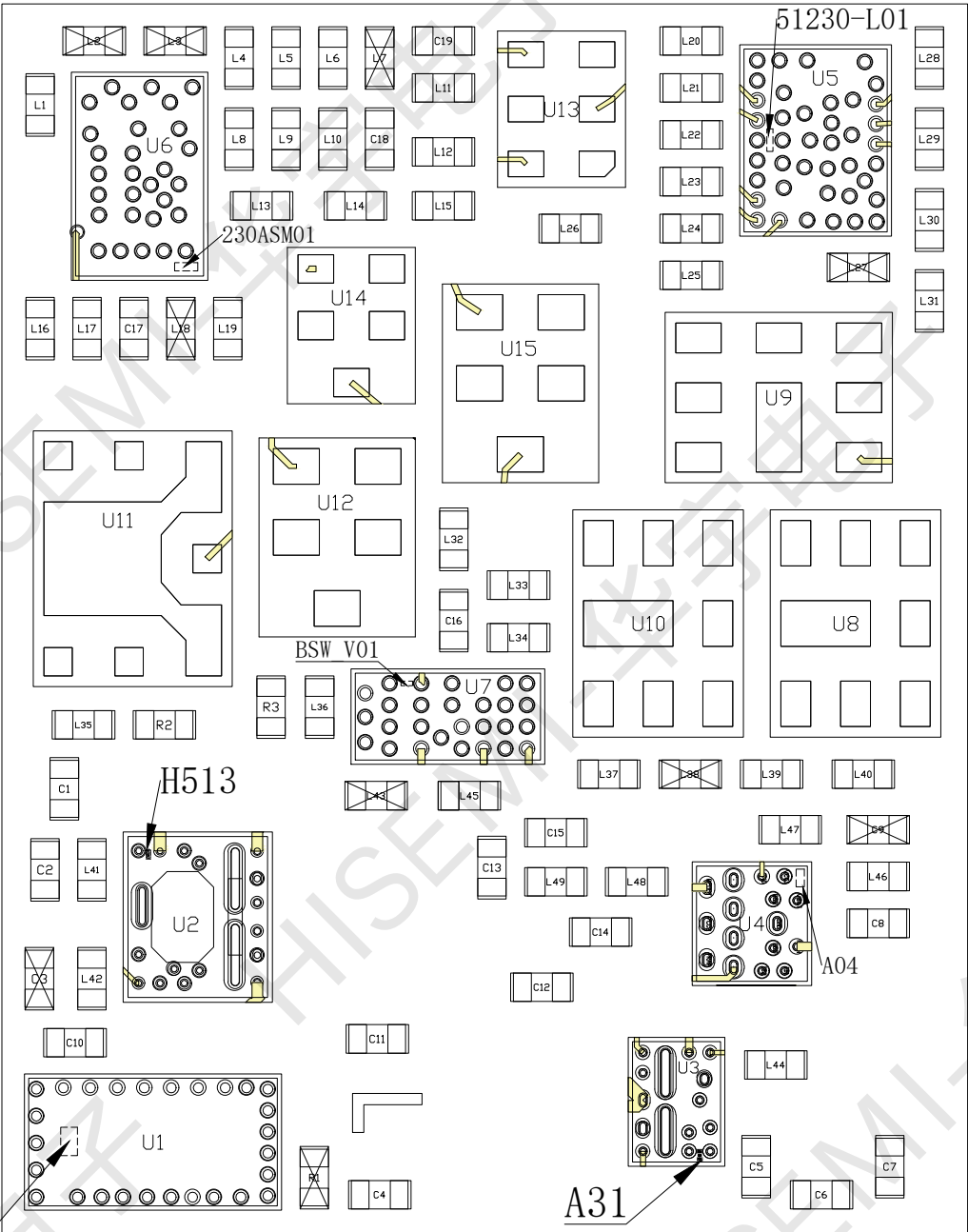
拟制 Prepared by		制图日期 Create Date	2025/12/9	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
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 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.		1200	线图号 Drawing No.	HY-PX-1200-076 A		页码 Page 6/ 15
			产品名称 Product Type		STR51230-11 E1.3		封装外型 PKG Type
助焊剂 Flux	--	--	--	--	--	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
TAC026S	--	--	--	--	--	首选(Preferred): EME-G311Q Type L ver.GR 备选(Optional):	S53011BY2E
客户图号 Customer drawing NO.							

样品验证，禁止量产！

PIN1



底部示意图

框架传送方向(装片): L/F Direction (D/A): 三圆孔朝上	实物图: Chip photo:	特殊说明 Special Instructions : HY-PX-1200-076 A 是HY-PX-1200-068 A 升级, 变更电感, 原图纸作废。
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拟制 Prepared by	制图日期 Create Date	2025/12/9	生效日期 Effective Date	客户确认签字/盖章: Customer Signature	
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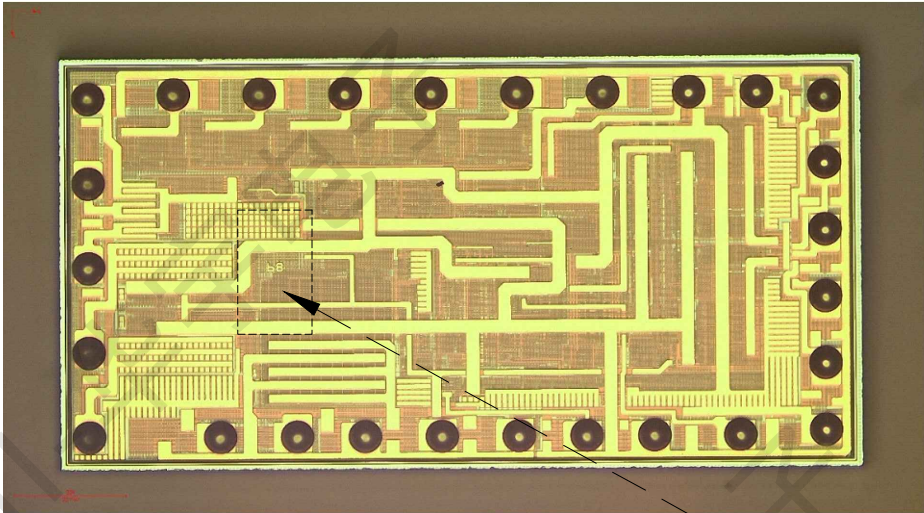
说明 Instructions	芯片名称 Die name	die ID	晶圆材质 Wafer material	芯片尺寸 Die Size (with scribe line)	Bump type*	Bump composition*	Min bump pitch (space + bump size)* UM	Min bump height* UM	Min bump diameter* UM	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否是激光切割？	减薄厚度 (μm) Wafer Thickness
U1	WSI530CD1E	P8	Si	1810X960 (um ²) 71.25X37.79 (mil ²)	Pillar bump	68um (35Cu+3Ni+30SnAg)	150	68	70	60	8	否/NO	200
U2	WLN577GD1E	H513	GaAs	1192*1042 (um ²) 46.92X41.02 (mil ²)	Pillar bump	68 um (Cu 40um+Ni 3um +SnAg 25 um)	150	68	60	60	6	是/YES low-k	200
U3	WLN520GD2E	A31	GaAs	908*680 (um ²) 35.74X26.77 (mil ²)	Pillar bump	68 um (Cu 40um+Ni 3um +SnAg 25 um)	133.5	68	60	60	6	是/YES low-k	200
U4	WLN577GD1E	A04	GaAs	870X840 (um ²) 34.25X33.07 (mil ²)	Pillar bump	68um (35Cu+3Ni+30SnAg)	160	68	60	60	6	是/YES low-k	200
U5	WUM530SD2E	51230-L01	Si	1347X1068 (um ²) 63.03X42.04 (mil ²)	Pillar bump	68um (35Cu+3Ni+30SnAg)	140	68	80	60	8	否/NO	200
U6	WUM530SD2E	230ASM01	Si	1464X960 (um ²) 57.63X37.79 (mil ²)	Pillar bump	68um (35Cu+3Ni+30SnAg)	144	68	80	60	8	否/NO	200
U7	WUM530SD2E	BSW_V01	Si	1365X672 (um ²) 53.74X26.45 (mil ²)	Pillar bump	68um (35Cu+3Ni+30SnAg)	153	68	80	60	8	否/NO	200

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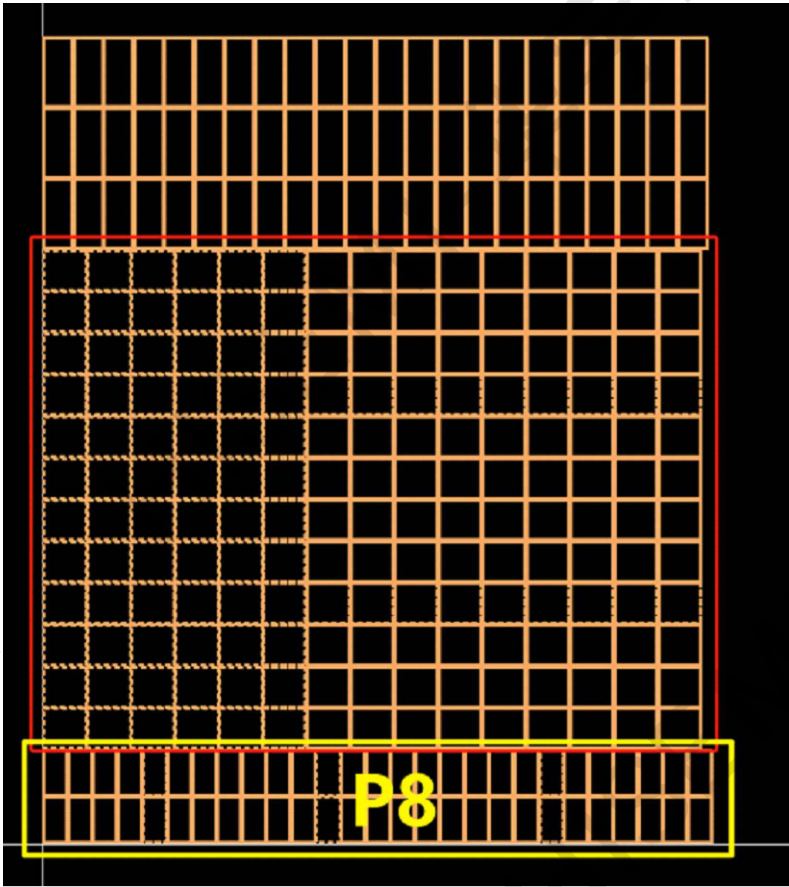
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U1取片图 (TOP VIEW):

样品验证，禁止量产！

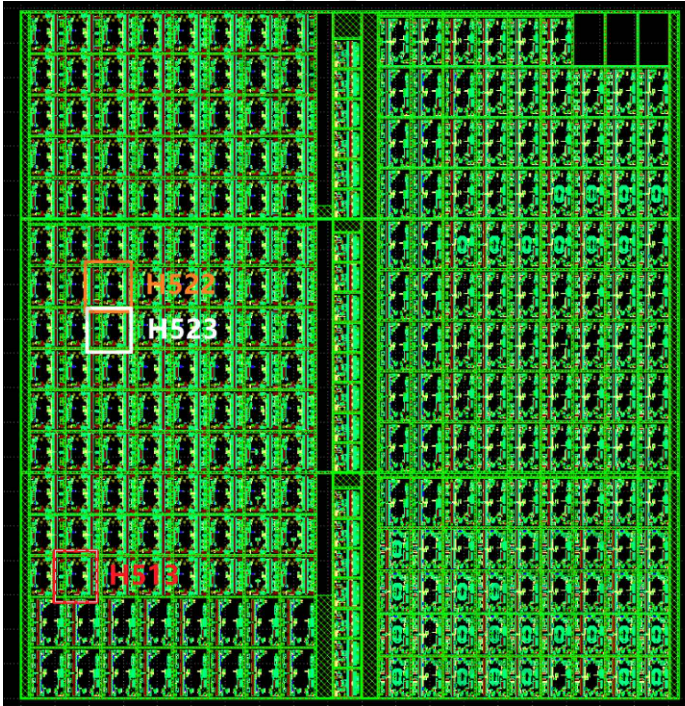
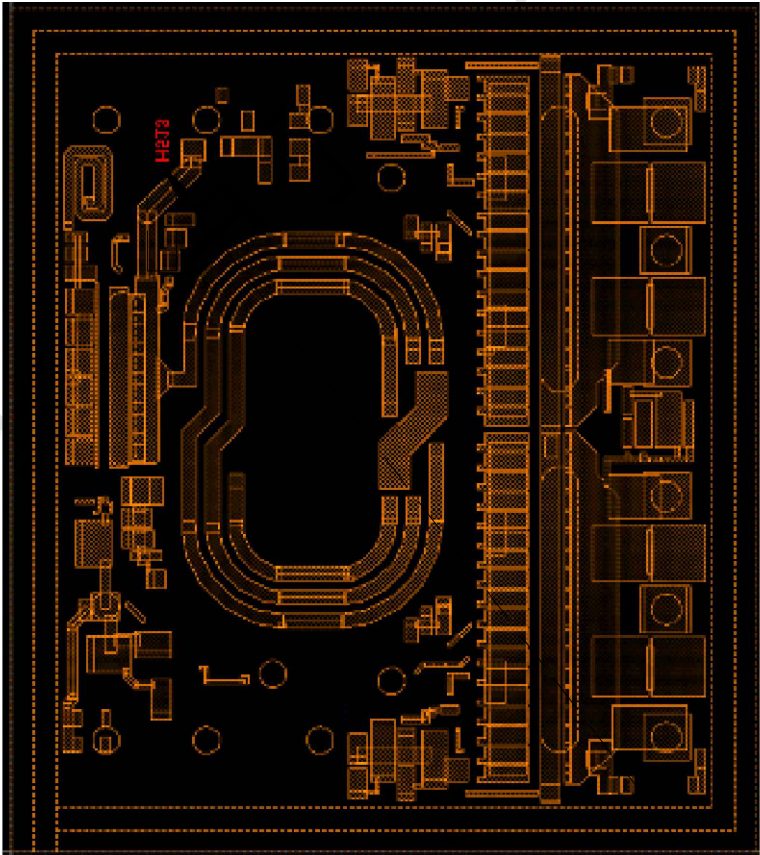


按目标区域取DIE：
ID：P8



U2取片图 (TOP VIEW):

样品验证，禁止量产！



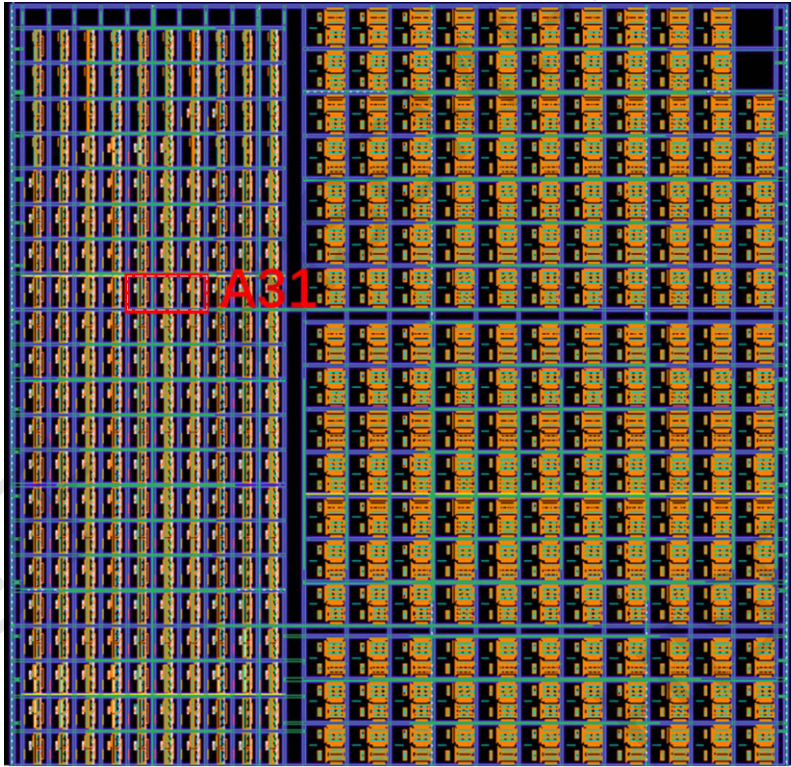
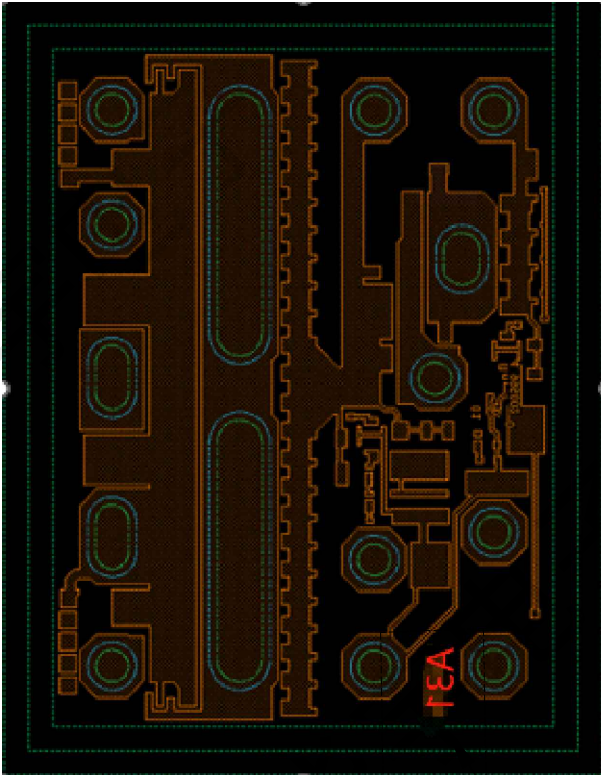
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拟制 Prepared by		制图日期 Create Date	2025/12/9	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
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U3取片图 (TOP VIEW):

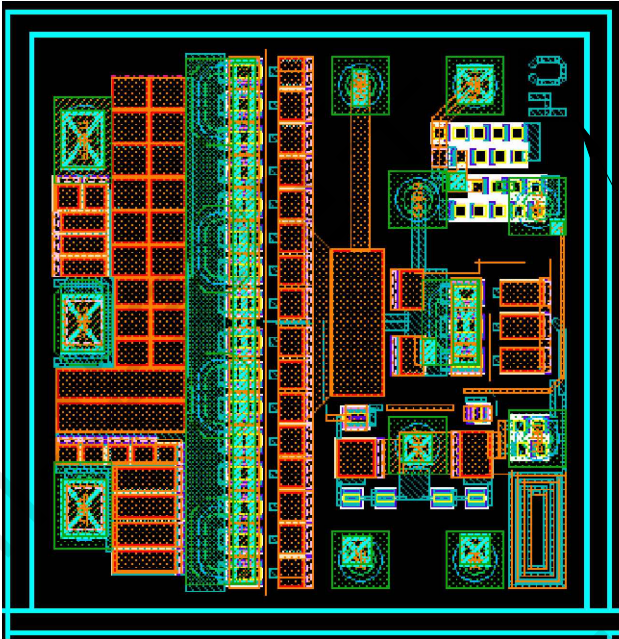
样品验证，禁止量产!



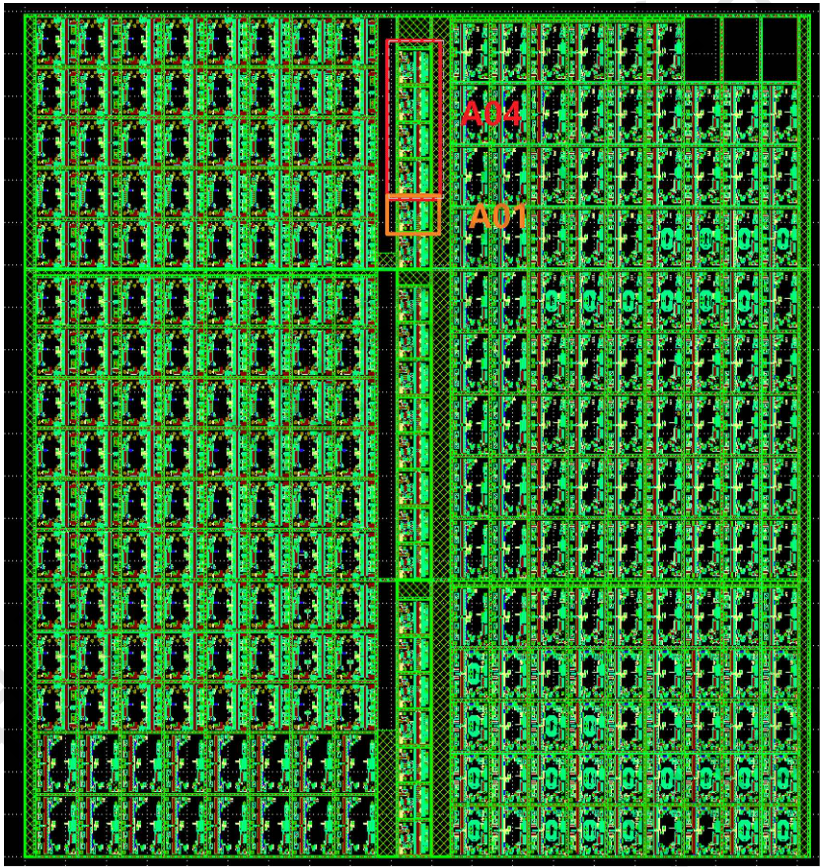
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U4取片图 (TOP VIEW):

样品验证，禁止量产！



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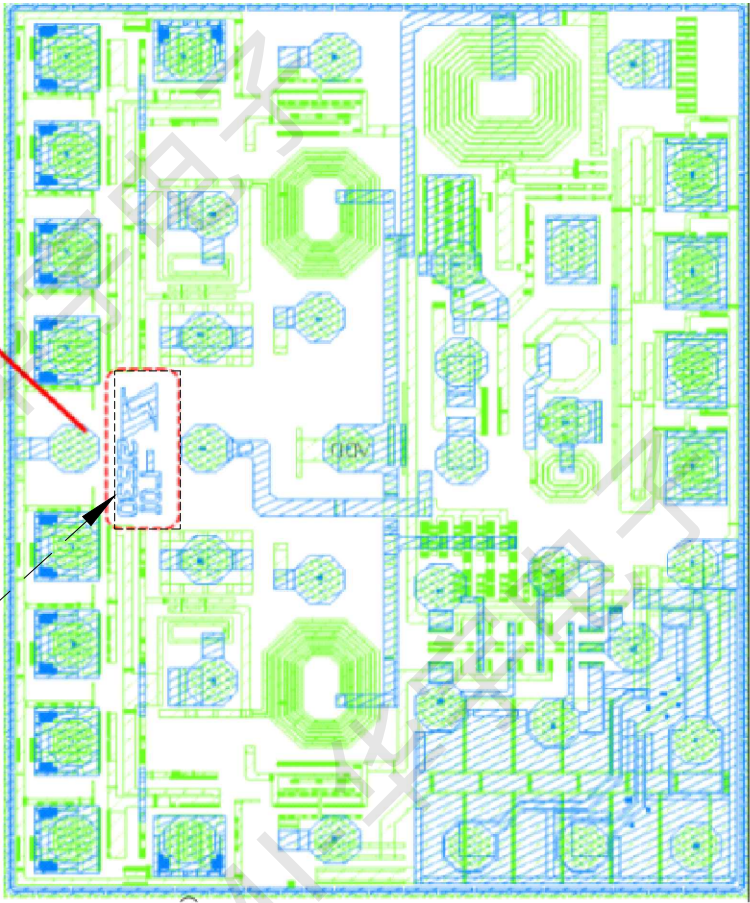


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研发审核 R&D check		产品工程审核 Product engineering check		批准 Approved by		

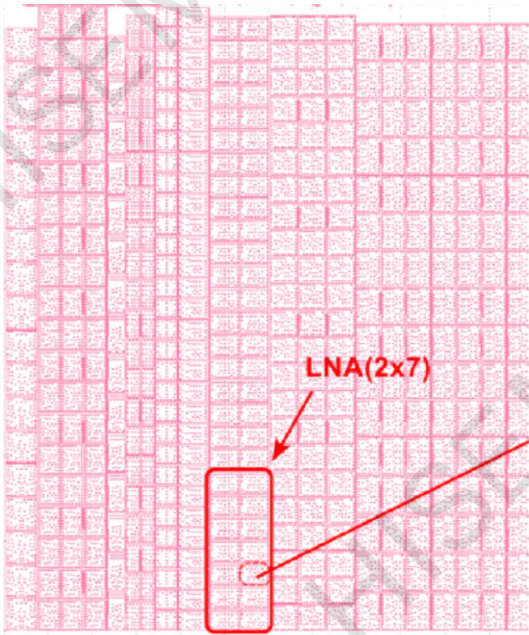
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U5取片图 (TOP VIEW):

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按目标区域取DIE:
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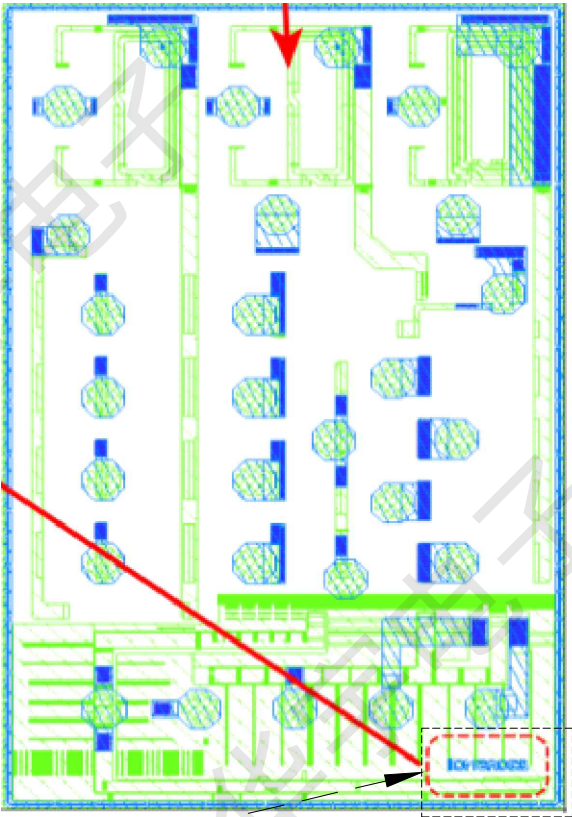
LNA(2x7)

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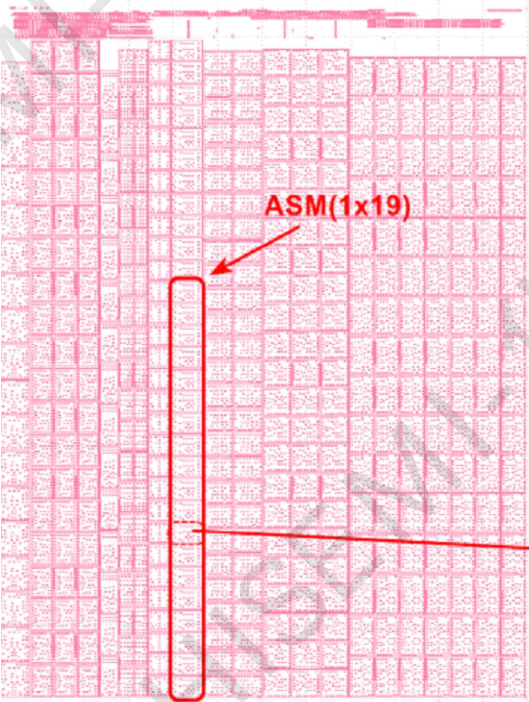
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U6取片图 (TOP VIEW):

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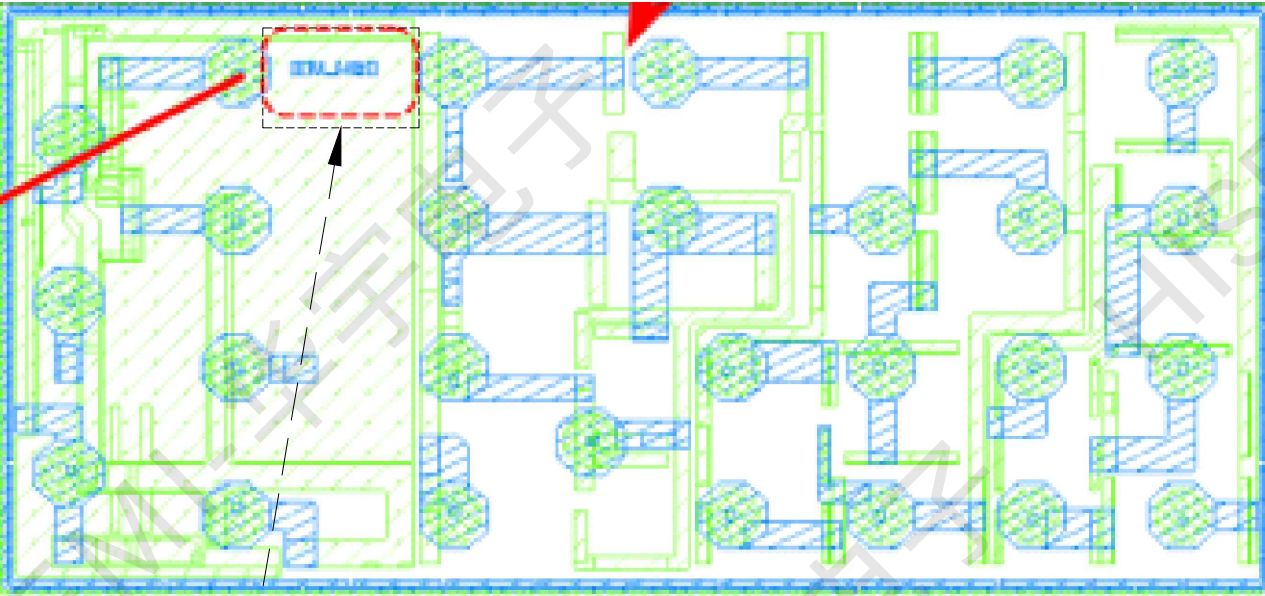


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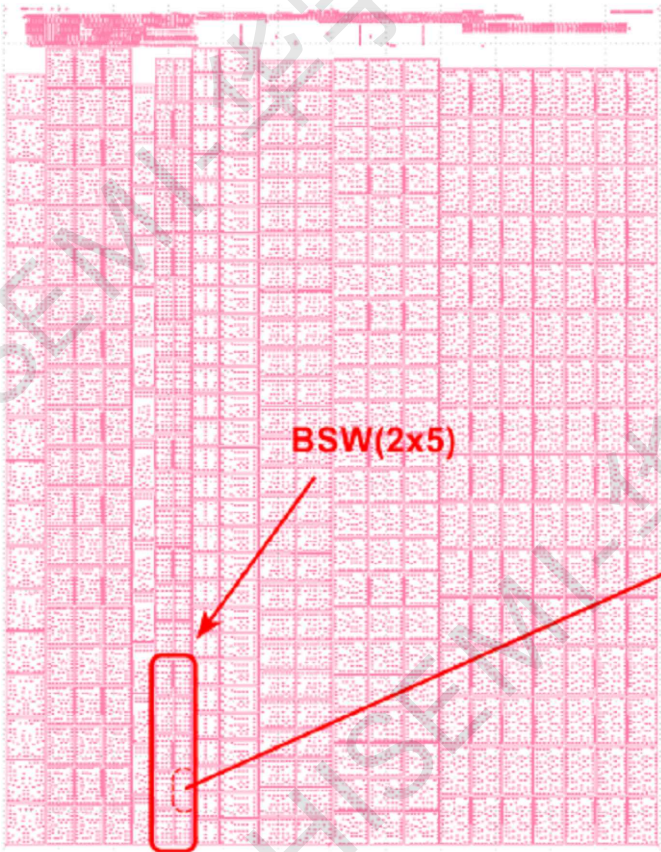
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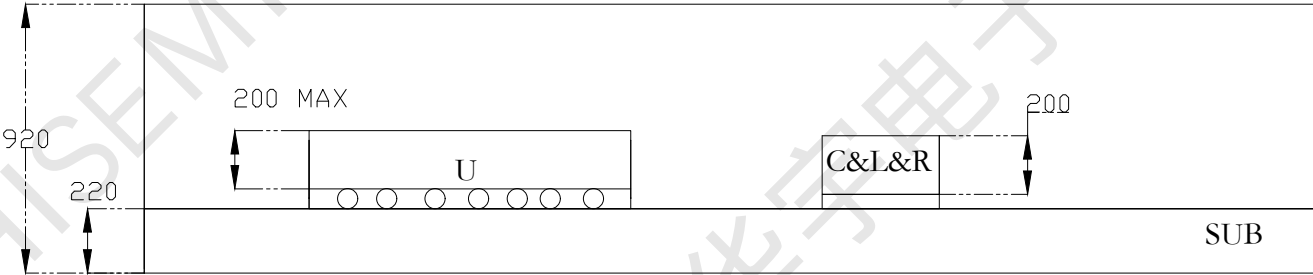


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 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.	1200	线图号 Drawing No.	HY-PX-1200-076 A		页码 Page 15 / 15
	产品名称 Product Type	STR51230-11 E1.3		封装外型 PKG Type	LGA247L(6.8×8.65×0.92-P0.45)	

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